



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 10/014,310  
Filing Date ..... December 11, 2001  
Inventor ..... Ritesh P. Shah, et al.  
Assignee ..... Honeywell International Inc.  
Group Art Unit ..... 1753  
Examiner ..... A. Oltmans  
Attorney's Docket No. .... 32120-CON1  
Title: Methods of Forming Metal Articles

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

References –See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

Dated: 01 Dec 2003

By: James E. Lake  
James E. Lake  
Reg. No. 44,854

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JC67 2003 PCT/US01/265V U.S. PATENT & TRADEMARK OFFICE		JC67 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 32120-CON1	SERIAL NO. 10/014,310			
DEC 01 2003 LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT Ritesh P. Shah, et al.						
		FILING DATE December 11, 2001		GROUP 1753				
U.S. PATENT DOCUMENTS								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	4,844,746	07/1989	Hormann et al				
	AB	6,521,173	02/2003	Kumar				
	AC	6,454,994	09/2002	Wang				
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
	AM	JP-H03-197640A	08/1991	Japan			Yes	No
	AN	EP 0902102 A1	08/1998	EPO				
	AO	EP 0281141 B2	03/1988	EPO				
	AP	JP59227992A	12/1984	Japan				
	AQ							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AR		"Nickel, Cobalt and Their Alloys". pub. By ASM International, December 2000, pages 76, 230-234.					
	AS		S. Sawada, "On Advanced Sputtering Targets of Refractory Metals and Their Silicides for VLSI-Applications", 12 <sup>th</sup> International Plansee Seminar, 1989, Top 5: Ultrapure Refractory Metals, pgs. 207, 216.					
	AT		P. Ding et al, "Copper Barrier, Seed Layer, and Planarization Technologies", June 10-12, 1997 VMIC Conference 1997, ISMIC-107/97/0087(c), pgs. 87-92.					
EXAMINER				DATE CONSIDERED				
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>								

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